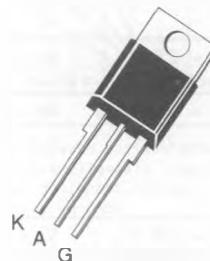


THYRISTORS

- GLASS PASSIVATED CHIP
- POSSIBILITY OF MOUNTING ON PRINTED CIRCUIT
- AVAILABLE IN NON-INSULATED VERSION → TYN SERIES OR IN INSULATED VERSION → TXN SERIES (INSULATING VOLTAGE 2500 V_{RMS})
- UL RECOGNIZED FOR TXN SERIES (E81734)



TO 220 AB
(Plastic)

DESCRIPTION

SCR's designed for motor control, heating controls, power supplies...

ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value		Unit
I _{T(RMS)}	RMS on-state Current (1)	T _c = 75 °C	8	A
I _{T(AV)}	Mean on-state Current (1)	T _c = 75 °C	5	A
I _{TSM}	Non Repetitive Surge Peak on-state Current (T _j initial = 25 °C) (2)	t = 8.3 ms	84	A
		t = 10 ms	80	
I ² t	I ² t Value for Fusing	t = 10 ms	32	A ² s
di/dt	Critical Rate of Rise of on-state Current (3)		50	A/μs
T _{stg} T _j	Storage and Operating Junction Temperature Range	- 40 to 110		°C
		- 40 to 110		°C

Symbol	Parameter	TXN/TYN ..., G, K							Unit
		058	108	208	408	608	808	1008	
V _{DRM} V _{RRM}	Repetitive Peak off-state Voltage (4)	50	100	200	400	600	800	1000	V

(1) Single phase circuit, 180° conduction angle.

(2) Half sine wave

(3) I_G = 400 mA di/dt = 1 A/μs

(4) T_j = 110 °C.

THERMAL RESISTANCES

Symbol	Parameter	Value		Unit
R _{th} (j-c) R _{th} (j-a)	Junction-case for D.C. Junction-ambient	4.7 60		°C/W °C/W

GATE CHARACTERISTICS (maximum values) $P_{GM} = 20 \text{ W}$ ($t_p = 20 \mu\text{s}$) $I_{FGM} = 2 \text{ A}$ ($t_p = 20 \mu\text{s}$) $V_{RGM} = 5 \text{ V}$ $P_G(\text{AV}) = 0.5 \text{ W}$ $V_{FGM} = 15 \text{ V}$ ($t_p = 20 \mu\text{s}$)**ELECTRICAL CHARACTERISTICS**

Symbol	Test Conditions			Min.	Typ.	Max.	Unit		
I_{GT}	$T_j = 25^\circ\text{C}$	$V_D = 12 \text{ V}$	$R_L = 33 \Omega$	Without Suffix		15	mA		
				Suffix G		25			
				Suffix K		40			
V_{GT}	$T_j = 25^\circ\text{C}$			$V_D = 12 \text{ V}$	$R_L = 33 \Omega$		1.5	V	
Pulse Duration > 20 μs									
V_{GD}	$T_j = 110^\circ\text{C}$	$V_D = V_{DRM}$	$R_L = 3.3 \text{ k}\Omega$		0.2			V	
I_H	$T_j = 25^\circ\text{C}$	$I_T = 100 \text{ mA}$	Gate Open	Without Suffix		30	mA		
				Suffix G		45			
				Suffix K		60			
I_L	$T_j = 25^\circ\text{C}$	$V_D = 12 \text{ V}$	$I_G = 80 \text{ mA}$			50		mA	
Pulse Duration > 20 μs									
V_{TM}	$T_j = 25^\circ\text{C}$	$I_{TM} = 16 \text{ A}$	$t_p = 10 \text{ ms}$				1.6	V	
I_{DRM}	V_{DRM} Specified			$T_j = 25^\circ\text{C}$		0.01	mA		
				$T_j = 110^\circ\text{C}$		1			
I_{RRM}	V_{RRM} Specified			$T_j = 25^\circ\text{C}$		0.01	mA		
				$T_j = 110^\circ\text{C}$		1			
t_{gI}	$T_j = 25^\circ\text{C}$	$V_D = V_{DRM}$	$dI_G/dt = 0.45 \text{ A}/\mu\text{s}$	$I_T = 16 \text{ A}$		2		μs	
t_q	$T_j = 110^\circ\text{C}$	$I_T = 16 \text{ A}$	$dI/dt = 30 \text{ A}/\mu\text{s}$	$V_R = 25 \text{ V}$		70		μs	
dv/dt^*	$dv/dt = 50 \text{ V}/\mu\text{s}$			Gate Open			V/ μs		
				Without Suffix	200				
				Suffix G	500				
				Suffix K	750				

* For higher guaranteed values, please consult us.

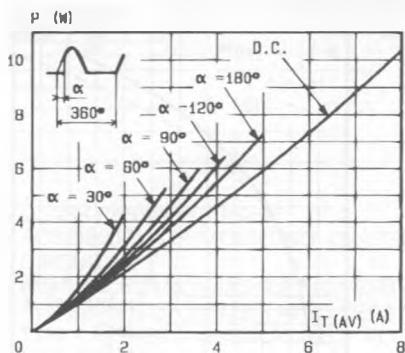


Fig.1 - Maximum mean power dissipation versus mean on-state current.

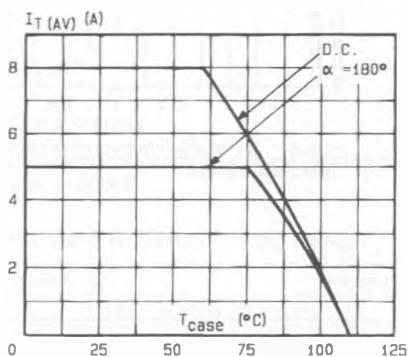


Fig.3 - Mean on-state current versus case temperature.

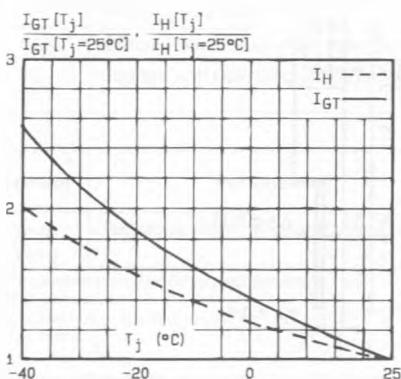


Fig.5 - Relative variation of gate trigger current and holding current versus junction temperature.

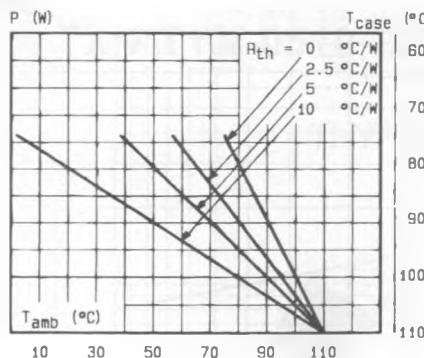


Fig.2 - Correlation between maximum mean power dissipation and maximum allowable temperatures (T_{amb} and T_{case}) for different thermal resistances heatsink + contact.

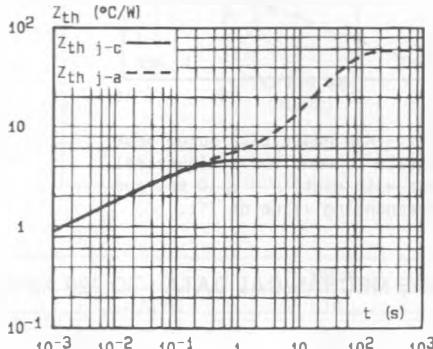


Fig.4 - Thermal transient impedance junction to case and junction to ambient versus pulse duration.

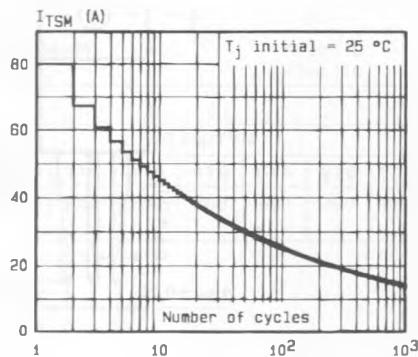


Fig.6 - Non repetitive surge peak on-state current versus number of cycles.

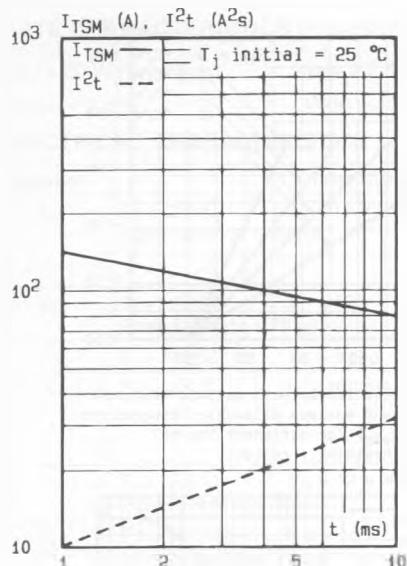


Fig.7 - Non repetitive surge peak on-state current for a sinusoidal pulse with width : $t \leq 10$ ms, and corresponding value of I^2t .

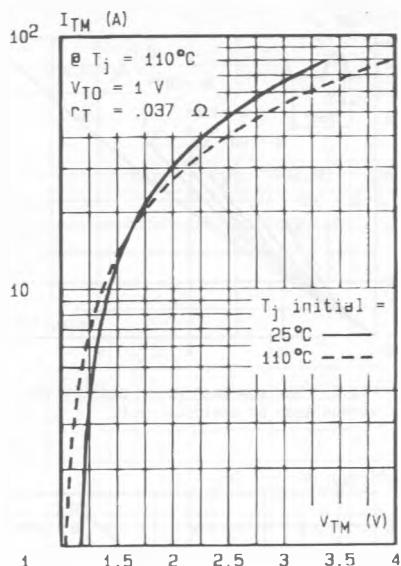
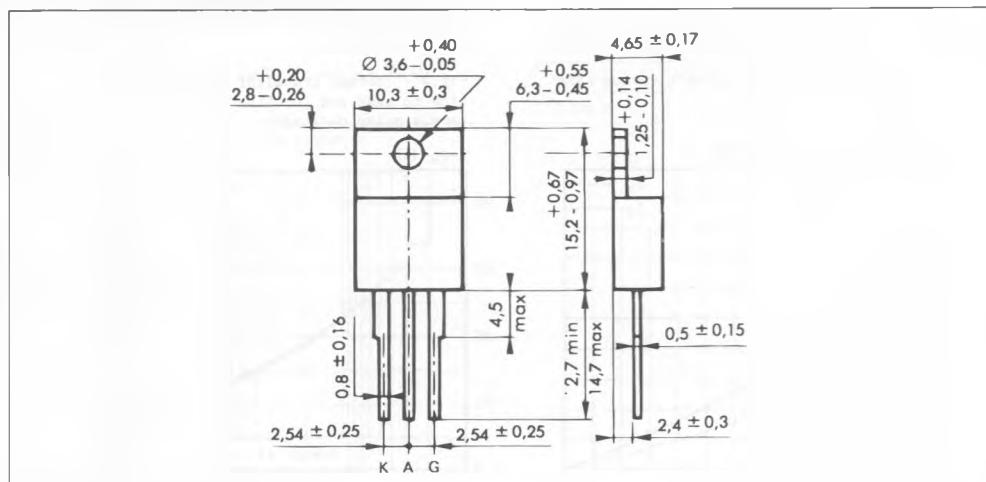


Fig.8 - On-state characteristics (maximum values).

PACKAGE MECHANICAL DATA : TO 220 AB Plastic



Cooling method : by conduction (method C)

Marking : type number

Weight : 2 g